

THERMAL CONDUCTIVE TAPE

series: TH



- Double sided pressure sensitive adhesive tape.
- Thermal Conductivity: 2.5w/mk.
- High bond strength to a variety of surfaces.
- Can be used to replace thermal filler pads and grease.
- Low thermal impedance.
- Typical applications include mounting heat sinks on processors, mounting heat spreaders onto PCBs and a replacement for heat cure adhesives and mechanical fixings.

Item	TH-10NF	Test Method
Sheet size (mm)	300x300	-
Adhesive Type	Acrylic Adhesive	-
Continuous Use Temp.	-40 ~ 120(°C)	-
Thickness	0.15/0.3mm	ASTM D374
Thickness Tolerance	0.02	ASTM D374
Voltage Breakdown	>3000 Vac	ASTM D149
Steel adhesion (g/25mm)	800	ASTM E 1000
Thermal Impedance @ 50psi	0.31	-
Thermal Conductivity	2.5 w/mk	ASTM D5470
Volume Resistivity (Ω-cm)	10 ¹⁴	ASTM D 257
Hardness (Shore A)	33 +/-5	JIS K 6301A
Holding Power (25°C/Hours)	> 48 Hours	PSTC-7
Holding Power (80°C/Hours)	> 48 Hours	PSTC-7